



IRP3216N18-D0

SMD Type 940nm Infrared Emitter

Features

- Small double-end package
- Viewing Angle = $\pm 15^\circ$
- High radiant intensity
- High reliability
- Good spectral matching to Si photo detector
- RoHS compliance

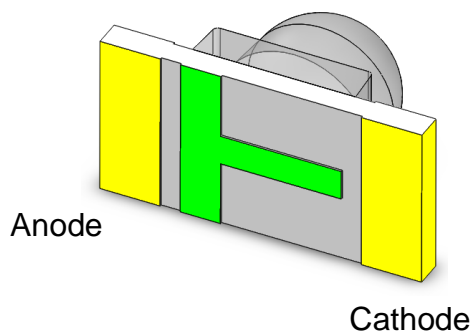
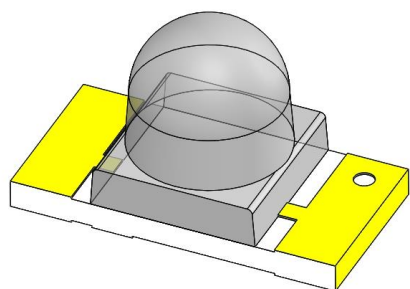
Applications

- Infrared sensor

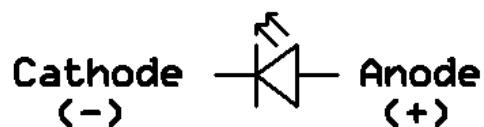
Description

The IRP3216N18-D0 is a GaAlAs infrared LED housed in a miniature SMD package. The device has a peak wavelength of 940nm LED spectrally matched with phototransistor or photodiode.

Package Outline



Schematic



**Absolute Maximum Rating at 25°C**

Symbol	Parameters	Ratings	Units	Notes
I _F	Continuous Forward Current	70	mA	
I _{FP}	Peak Forward Current	0.7	A	1
V _R	Reverse Voltage	5	V	
T _{opr}	Operating Temperature	-40 ~ +85	°C	
T _{stg}	Storage Temperature	-40 ~ +100	°C	
T _{sol}	Soldering Temperature	260	°C	2
P _D	Power Dissipation at(or below) 25°C Free Air Temperature	140	mW	
R _{THJA}	Junction to Ambient Thermal Resistance	540	°C/W	

Electro-Optical Characteristics TA = 25°C (unless otherwise specified)**Optical Characteristics**

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
I _e	Radiant Intensity	I _F =20mA	3.0	5.2	13	mW/sr	3
		I _F =70mA	-	18	-		
λ _p	Peak Wavelength	I _F =20mA	-	940	-	nm	
Δλ	Spectral Bandwidth	I _F =20mA	-	50	-	nm	
θ _{1/2}	Angle of Half Intensity	I _F =20mA	-	±15	-	deg	

Electrical Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V _F	Forward Voltage	I _F =20mA	1.1	1.20	1.35	V	
		I _F =70mA	1.2	1.34	1.54		
I _R	Reverse Current	V _R =5V	-	-	10	μA	

Notes:

- 1 : I_{FP} Conditions--Pulse Width ≤ 100μs and Duty ≤ 1%.
- 2 : Soldering time ≤ 5 seconds.
- 3 : I_e Bin Rank :

Bin Code	Fb	G	H
Min	3.0	4.0	6.5
Max	5.0	8.0	13



Typical Characteristic Curves

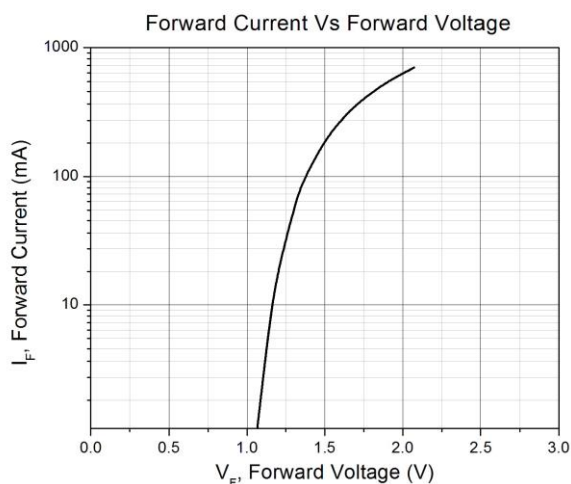


Figure 1

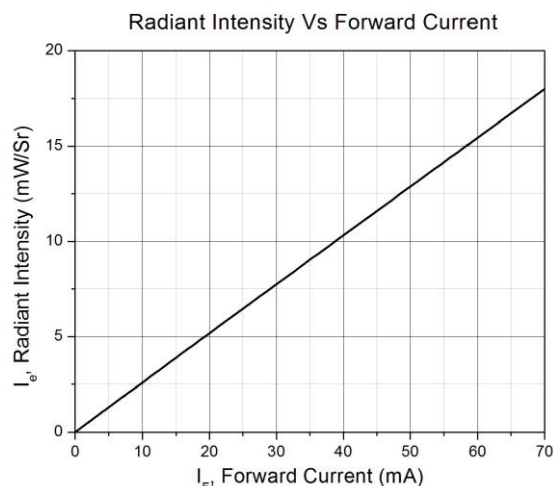


Figure 2

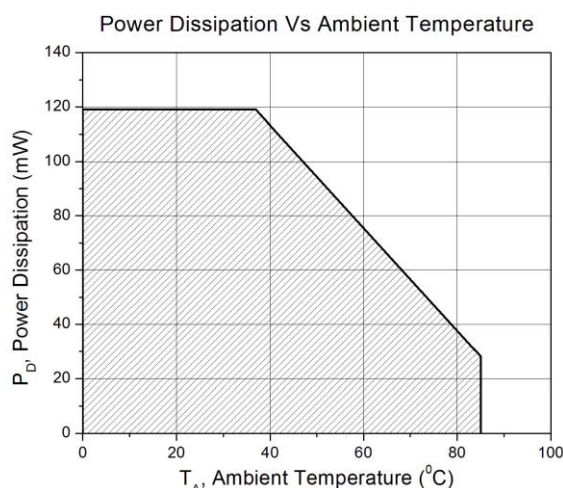


Figure 3

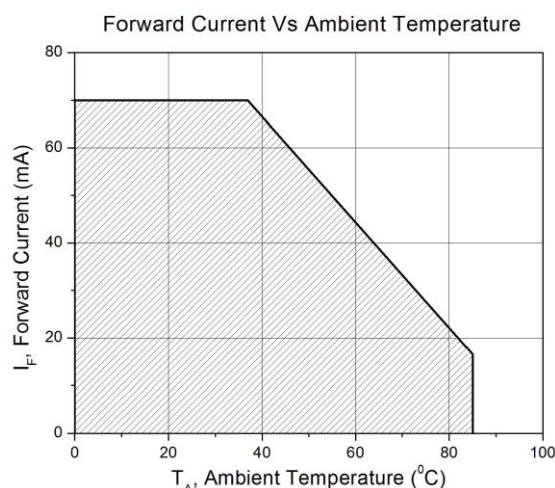


Figure 4

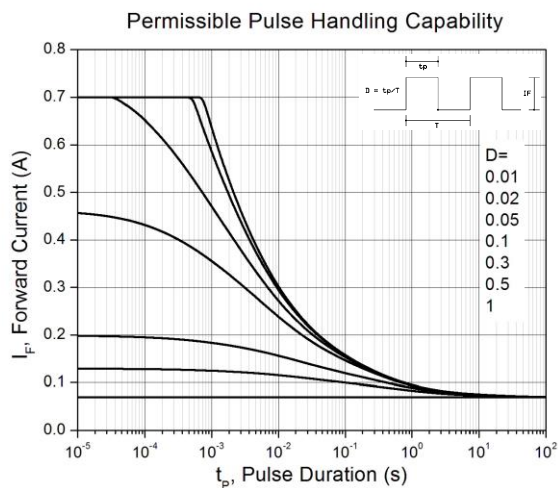


Figure 5

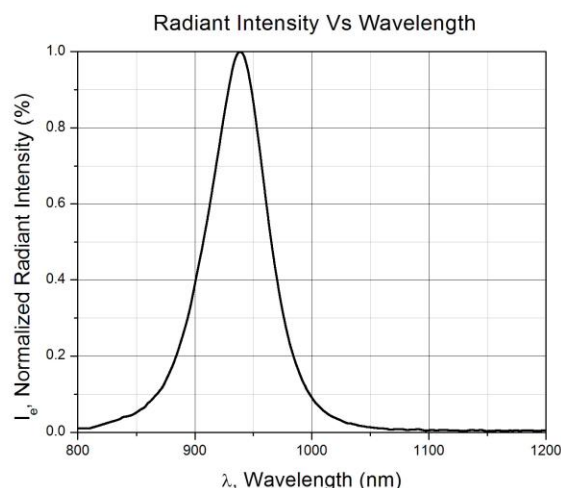


Figure 6



Typical Characteristic Curves

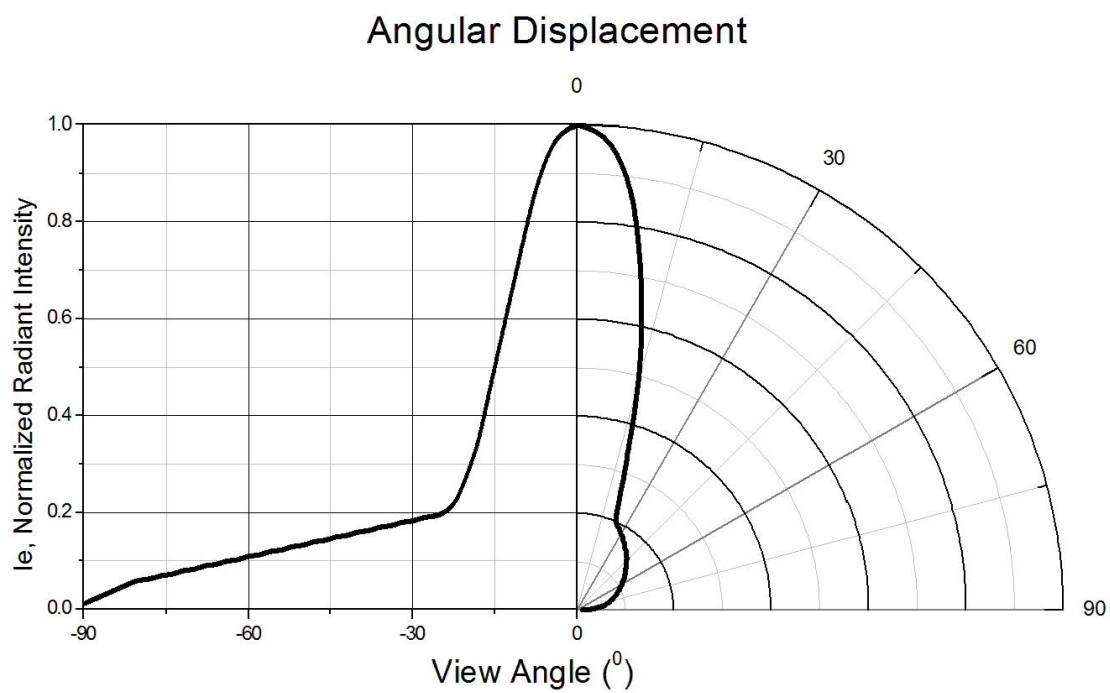
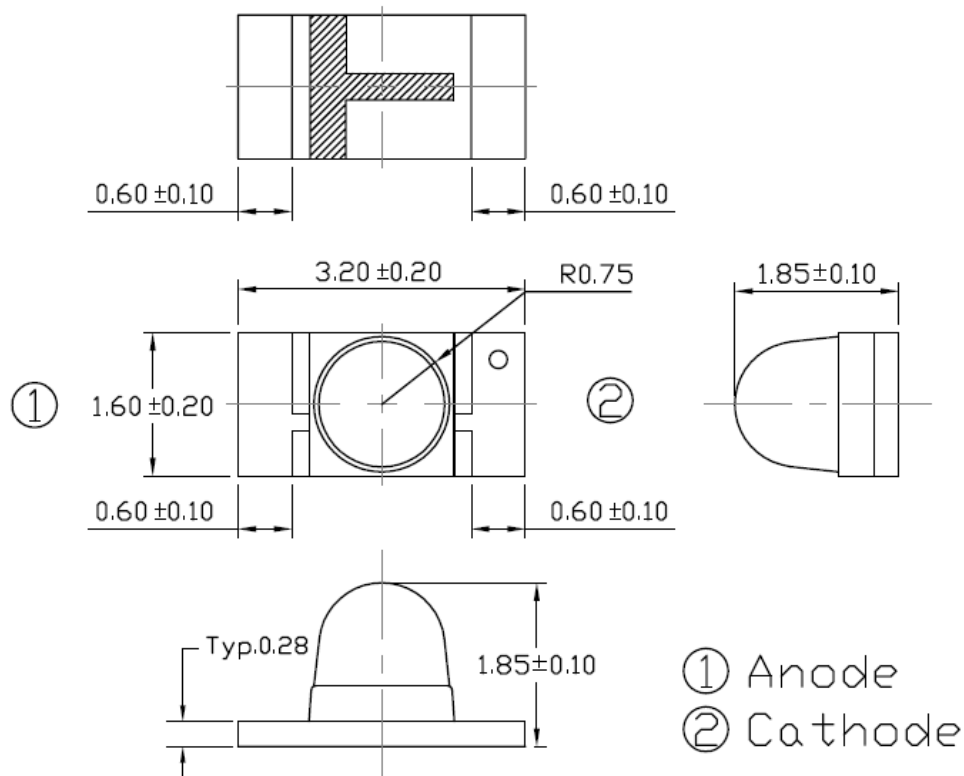


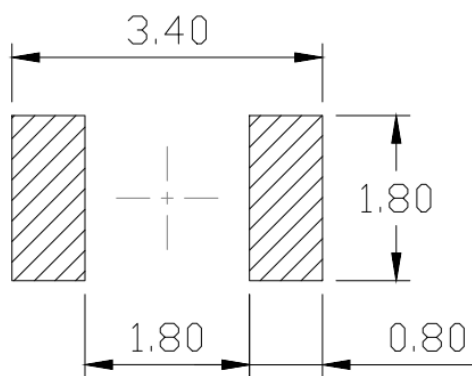
Figure 7



Package Dimension *All dimensions are in mm, unless otherwise stated*



Recommended Soldering Mask *All dimensions are in mm, unless otherwise stated*



Ordering Information

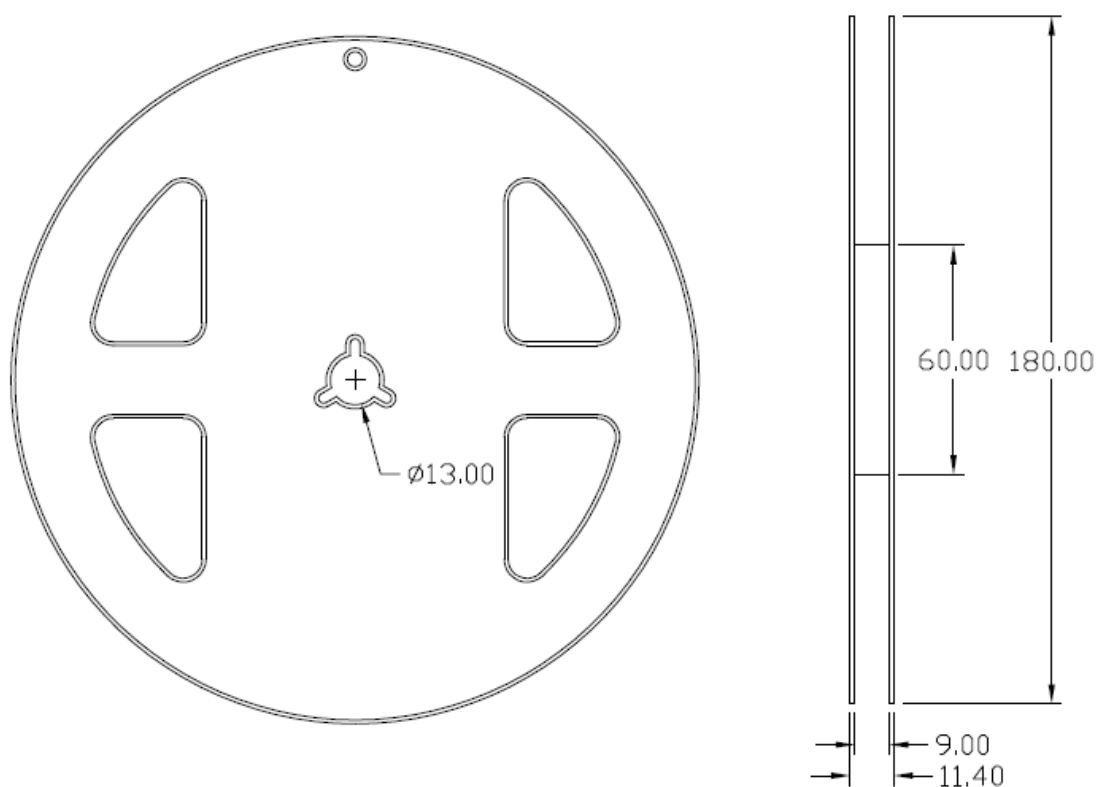
Part Number	Description	Quantity
IRP3216N18-D0(T1)	Tape & Reel	2000 pcs
IRP3216N18-D0(T2)	Tape & Reel	2000 pcs



IRP3216N18-D0

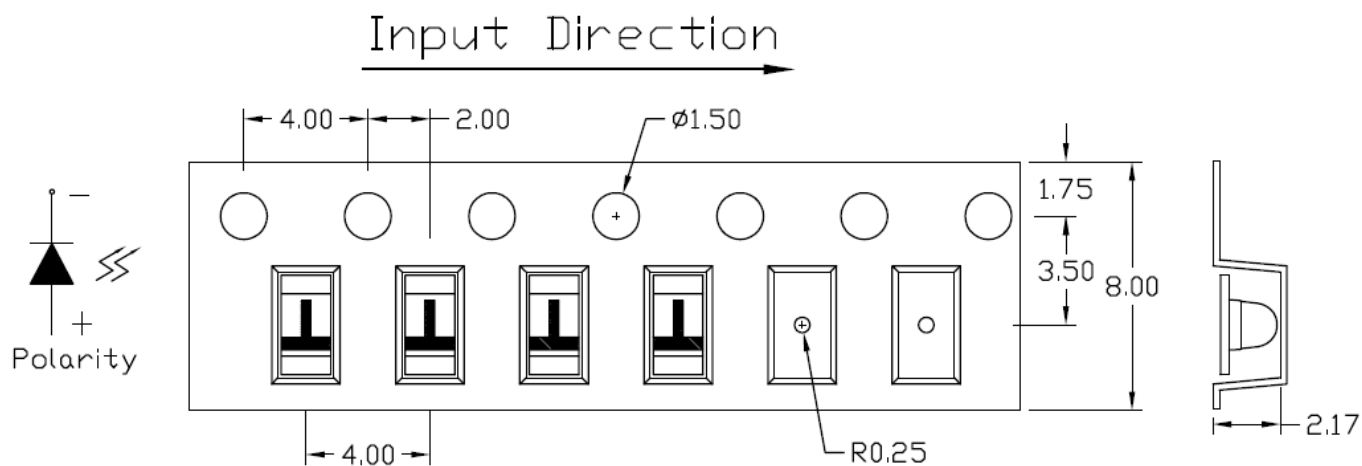
SMD Type 940nm Infrared Emitter

Reel Dimension *All dimensions are in mm, unless otherwise stated*



Tape Dimension *All dimensions are in mm, unless otherwise stated*

Part Number IRP3216N18-D0(T1)

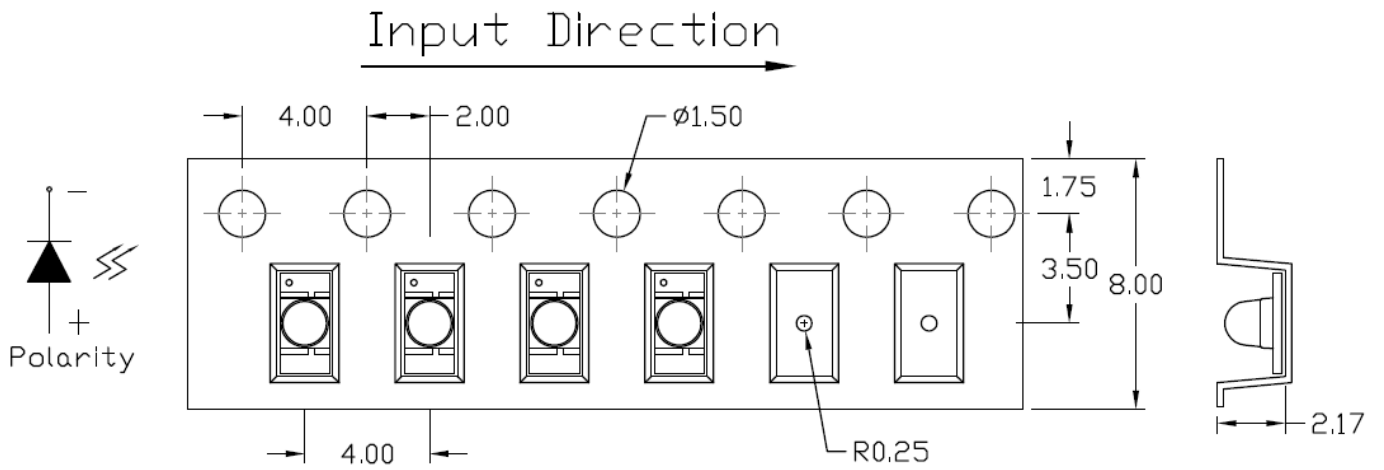




IRP3216N18-D0

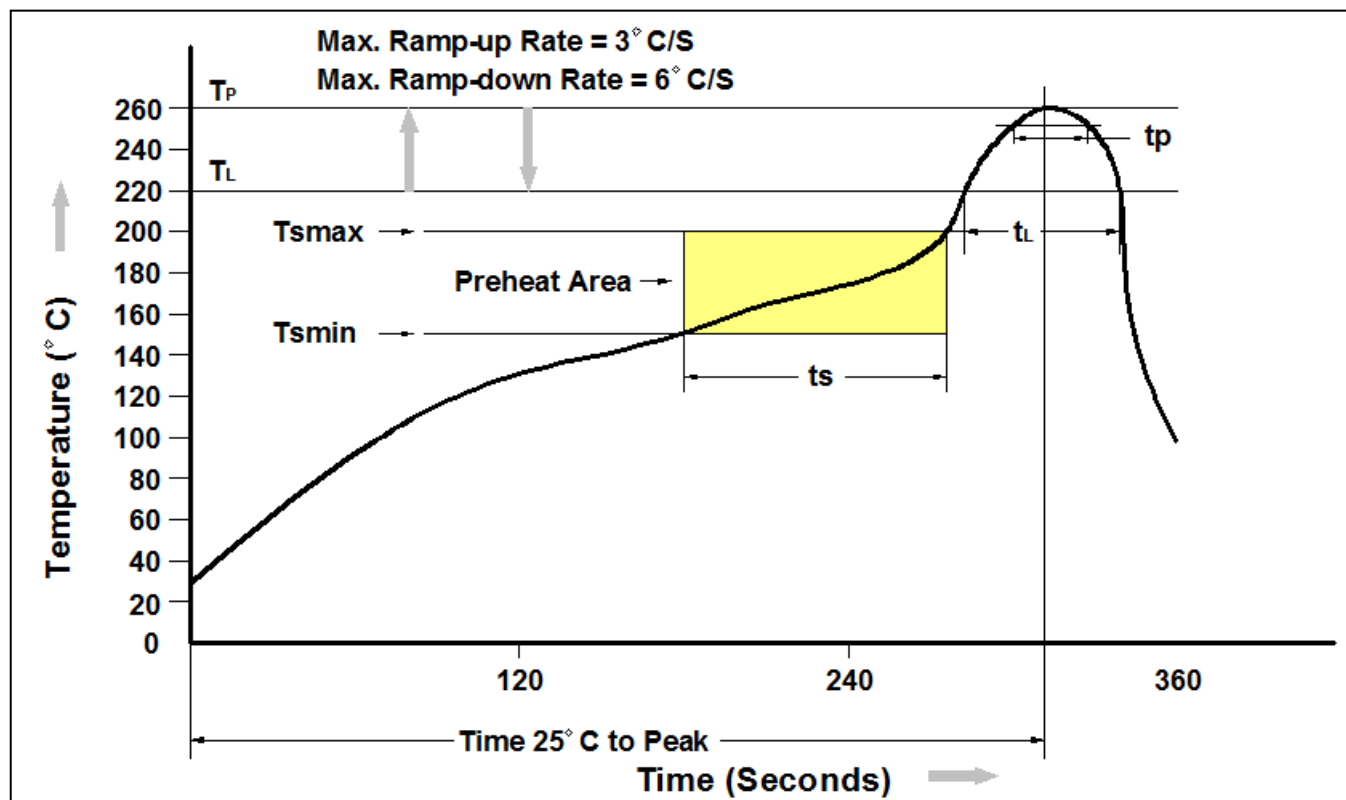
SMD Type 940nm Infrared Emitter

Part Number IRP3216N18-D0(T2)





Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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